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電源管理



顯示驅動



二三極管



LDO穩壓器



觸摸芯片



MOS管



運算放大器



存儲芯片



MCU



串口通信

SS3150-TD

產品規格說明書

3.0Amp Surface Mount Schottky Barrier Rectifiers

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250°C/10 seconds at terminals

Mechanical Data

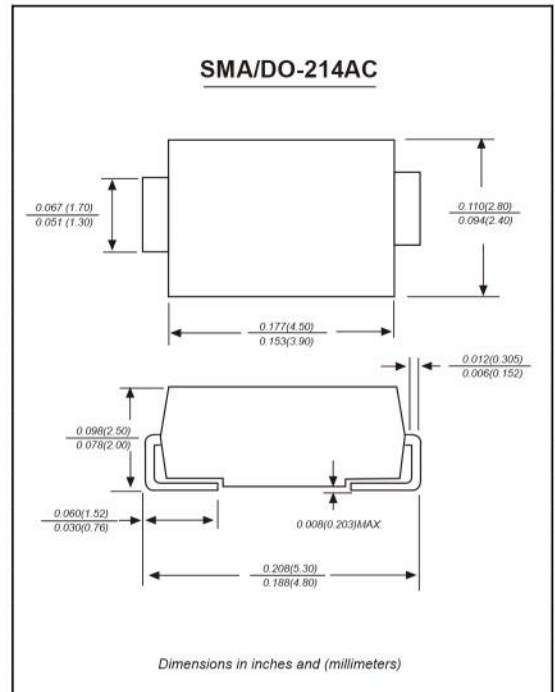
Case: JEDEC DO-214AC molded plastic body

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.002 ounce, 0.07 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SS32	SS34	SS36	SS38	SS310	SS315	SS320	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	150	200	VOLTS
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	105	150	VOLTS
Maximum DC blocking voltage	V _{DC}	20	40	60	80	100	150	200	VOLTS
Maximum average forward rectified current at T _A =75°C	I _(AV)	3.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	80.0							Amps
Maximum instantaneous forward voltage at 3.0A	V _F	0.55		0.70	0.85		0.95		Volts
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =100°C	I _R	0.5					0.2		mA
		20.0			10.0		2.0		
Typical thermal resistance (NOTE 1)	R _{θJA}	70.0							C/W
Operating junction temperature range	T _J	-55 to +125			-55 to +150				°C
Storage temperature range	T _{STG}	-55 to +150							°C

Note: 1.P.C.B. mounted with 8.0x8.0mm copper pad areas

Ratings And Characteristic Curves

SS32 THRU SS320

FIG. 1- FORWARD CURRENT DERATING CURVE

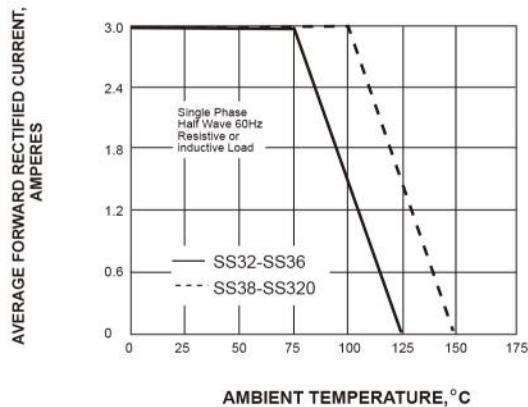


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

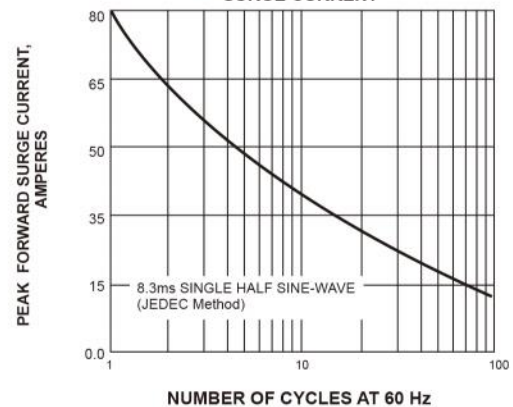


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

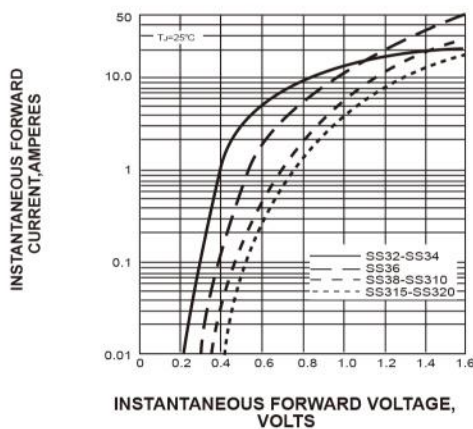


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

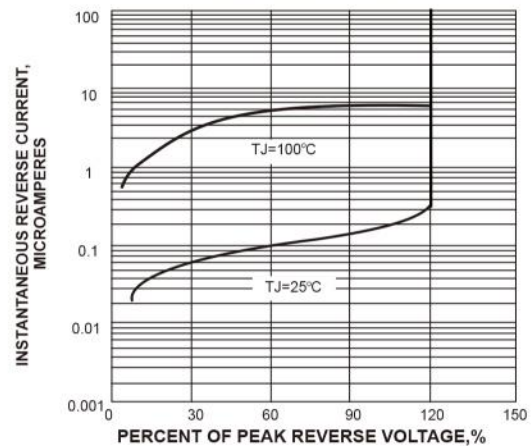


FIG. 5-TYPICAL TRANSIENT THERMAL IMPEDANCE

